

.025" SQ SOCKET HLE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com/HLE

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

BeCu

Plating:

Au over 50µ" (1,27µm) Ni

Current Rating:

2.5A @ 80°C ambient

Operating Temp Range:

-55°C to +125°C

Insertion Depth:

(1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry

Insertion Force:

(Single contact only)

Withdrawal Force:

(Single contact only)

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (02-20)

(0,15mm) .006" max (21-50)



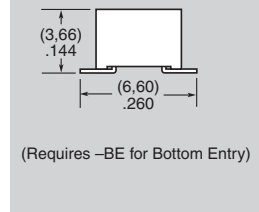
Mates With:
TSW, MTSW, DW,
EW, ZW, TLW, TSM,
MTLW, HW



-L
= 10µ" (0,25µm)
Gold on contact,
Gold Flash on tail

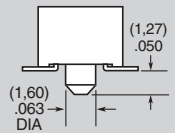
Note: Other Gold plating options available. Contact Samtec.

Leave blank for Surface Mount

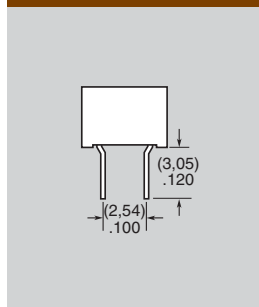


-BE
= Bottom Entry (Requires Surface Mount or -PE)

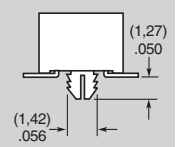
-A
= Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (N/A with -LC)



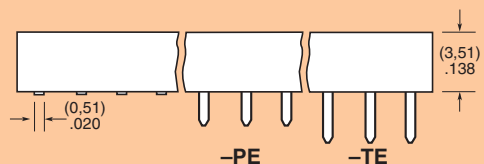
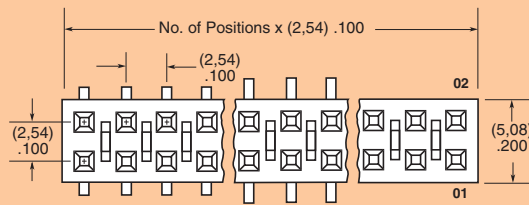
-TE
= Through-Hole Top Entry



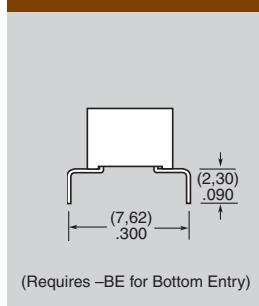
-LC
= Locking Clip (2 positions min.) (N/A with -A)



02 thru 50

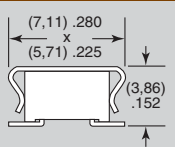


-PE
= Through-hole Pass Through Entry



-K
= (6,50mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option

-P
= Metal Pick & Place Pad (3 positions min.)



-TR
= Tape & Reel Packaging (29 positions max.)

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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